FAB NOTES:

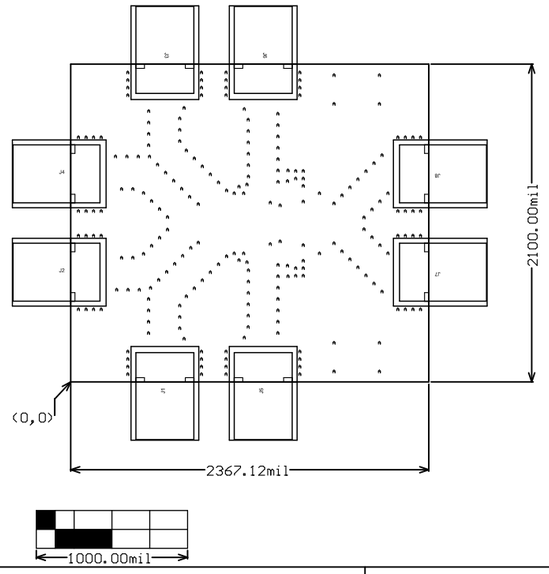
1. BOARD DIMENSION IS : 2367.124MIL x 2100MIL
2. VENDOR MAY ADJUST SOLDERMASK WHEREVER SOLDERMASK PADS ARE THE SAME SIZE (1:1) AS PER THE MANUFACTURING CAPABILITIES AND ALL OTHER SOLDER MASK PADS SHALL NOT BE MODIFIED, PROVIDED NO ADJACENT COPPER IS EXPOSED AND NO CONFLICT IS PRODUCED WITH ANY STATED "VIA TENTING/COVERING" REQUIREMENTS.
3. EXPOSED COPPER ARE PRESENT IN TOP AND BOTTOM LAYER AT 24 & 16 PLACES(Jx). THIS IS BY DESIGN. RUN AS IT IS.
4. ALL THE VIAS ARE TENTED ON TOP SIDE UNLESS OTHERWISE SOLDER MASK IS OPENED IN GERBER.
5. TRACES WITH 31MIL WITH 60MIL GROUND SPACING TO BE 50 OHMS +/-10% SINGLE ENDED ON EXTERNAL LAYER L1.

STACKUP TABLE:

	Layer	Name	Material	Thickness	Constant	Board Layer Stack
	1	Top Overlay				
	2	Top Solder	Solder Resist	0.80mil	3.5	
5	3	Top Layer	Copper	2.10mil		
	4	Dielectric1	MEGTRON-6	16.00mil	3.69	
	5	GND 1	Copper	1.40mil		
	6	Dielectric 2	FR-4	22.00mil	3.6	
	7	Power	Copper	1.40mil		
	8	Dielectric 3	FR-4	16.00mil	3.6	
	9	Bottom Layer	Copper	2.10mil		
	10	Bottom Solder	Solder Resist	0.80mil	3.5	

NOTE THIS IS AN IMPEDANCE CONTROLLED BOARD

1. ALL CORE AND PREPREG THICKNESSES ARE UP TO FAB SHOP TO SELECT.
2. EXTERNAL LAYER CU THICKNESSES ARE FINISHED THICKNESS AFTER PLATING.



DRILL TABLE:

	Symbol	Count	Hole Size	Plated	Hole Type	Tolerance(mils)
4	A	212	8.00mil (0.203mm)	PTH	Round	+0/-8
		212 Total				

DESIGN INFORMATION

MIN. TRACK WIDTH: 15 MIL
MIN. CLEARANCE: 7.8 MIL
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[] FR-408 [] FR-4 High Tg [X] OTHER REFER STACKUP
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [] BOTTOM
SILKSCREEN COLOR: [X] WHITE [] OTHER
SOLDER RESIST COLOR: [X] GREEN [] OTHER
[] MATTE [X] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [] ENEPIG
[] IMM. TIN/SILVER OR EQUIV [] OTHER
ARRAY/PANEL: [] CUT AND TRIM PER M1 BOARD OUTLINE
[] N.C. ROUTE [] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [] 1 [X] 2 [] 3
[X] RoHS [] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [] YES
BARE BOARD ELEC. TEST: [] NONE [X] REQUIRED [] PER ORDER
[] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: TLV3602EVM
DESIGNED FOR: Public Release
FILE NAME: AMPS155A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TLV3602EVM	REV: A
LAYER NAME = FAB	TID #: N/A	SVN REV: Not In VersionControl
PLOT NAME = Fabrication Drawing	GENERATED : 16-02-2022 12:43:40	TEXAS INSTRUMENTS

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ENGINEER: Joe Vanacore	LAYOUT BY: Tessolve
SCALE: 1.00	ALTIUM DESIGNER VERSION: 18.1.9.240

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